

F

F	
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E

E

D

D

C

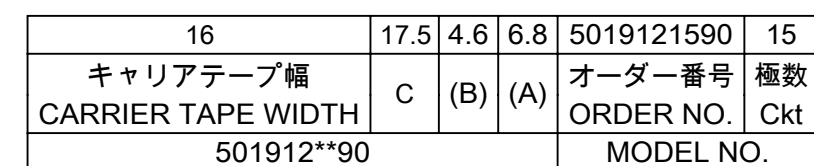
C

B

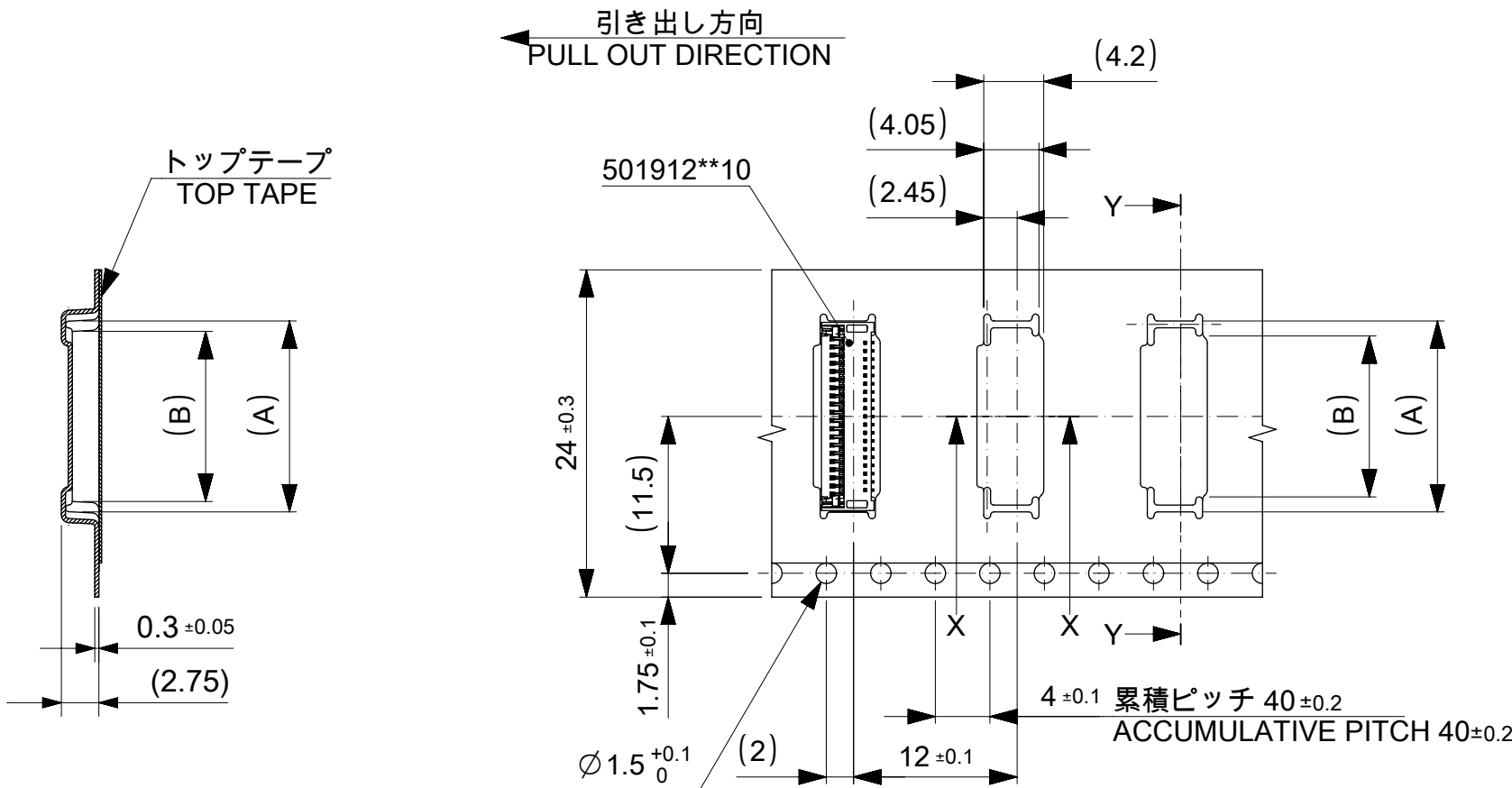
B

A

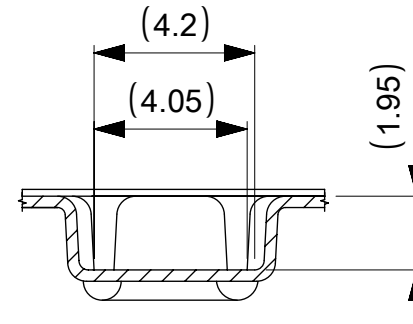
A



DOCUMENT STATUS	P1	RELEASE DATE	2024/05/13	16:22:02
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SECT. Y-Y



SECT. X-X

24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE

24	25.5	12.4	14.6	5019124190	41
		11.2	13.4	5019123790	37
		8.2	10.4	5019122790	27
		7.6	9.8	5019122590	25
		7.0	9.2	5019122390	23
		6.4	8.6	5019122190	21
キャリアテープ幅 CARRIER TAPE WIDTH	C	(B)	(A)	オーダー番号 ORDER NO.	極数 Ckt
501912**90				MODEL NO.	

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION															
DIMENSION UNITS		SCALE		CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#513405.				molex							
mm		NTS													
GENERAL TOLERANCES (UNLESS SPECIFIED)				EMBSTP PKG FOR 0.3 FPC CONN (HGT=1.8MM) GOLD PLATING											
ANGULAR TOL ± 3.0 °															
4 PLACES		± 0.2													
3 PLACES		± 0.2													
2 PLACES		± 0.2													
1 PLACE		± 0.2		PRODUCT CUSTOMER DRAWING				DOCUMENT NUMBER 5019120000		DOC TYPE PSD		DOC PART 000		REVISION B1	
0 PLACES		± 0.2													
EC NO: 784316				INITIAL REVISION: DRWN: SHIRATA 2015/11/24 APPR: YNOGAWA 2016/01/05											
DRWN: RAVINR1 2024/04/19															
CHK'D: GGA 2024/05/13															
APPR: GGA 2024/05/13															
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION		DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER		SHEET NUMBER	
						A3-SIZE		501912		SEE TABLE				3 OF 4	

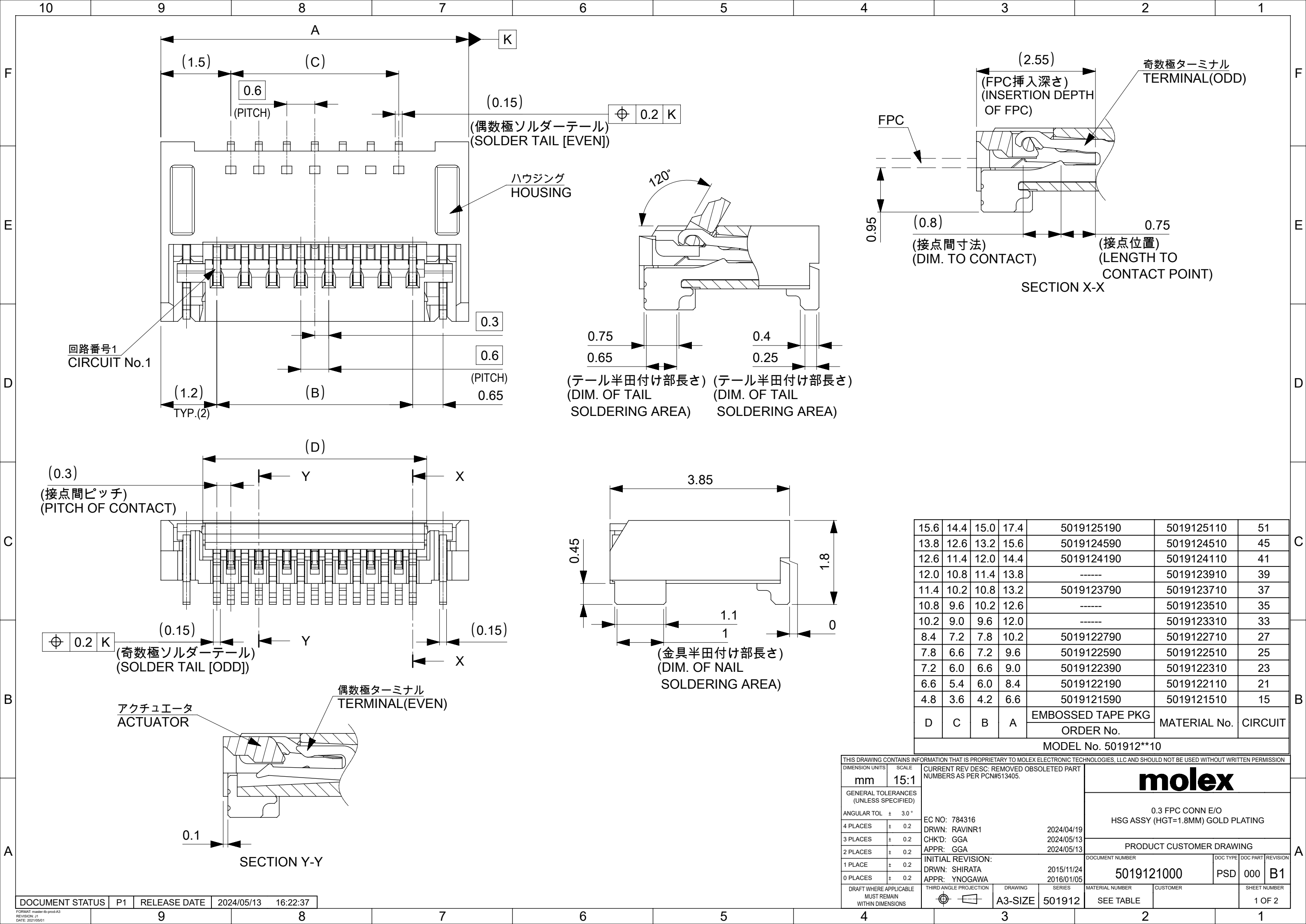
molex

EMBSTP PKG FOR 0.3 FPC CONN
(HGT=1.8MM) GOLD PLATING

PRODUCT CUSTOMER DRAWING

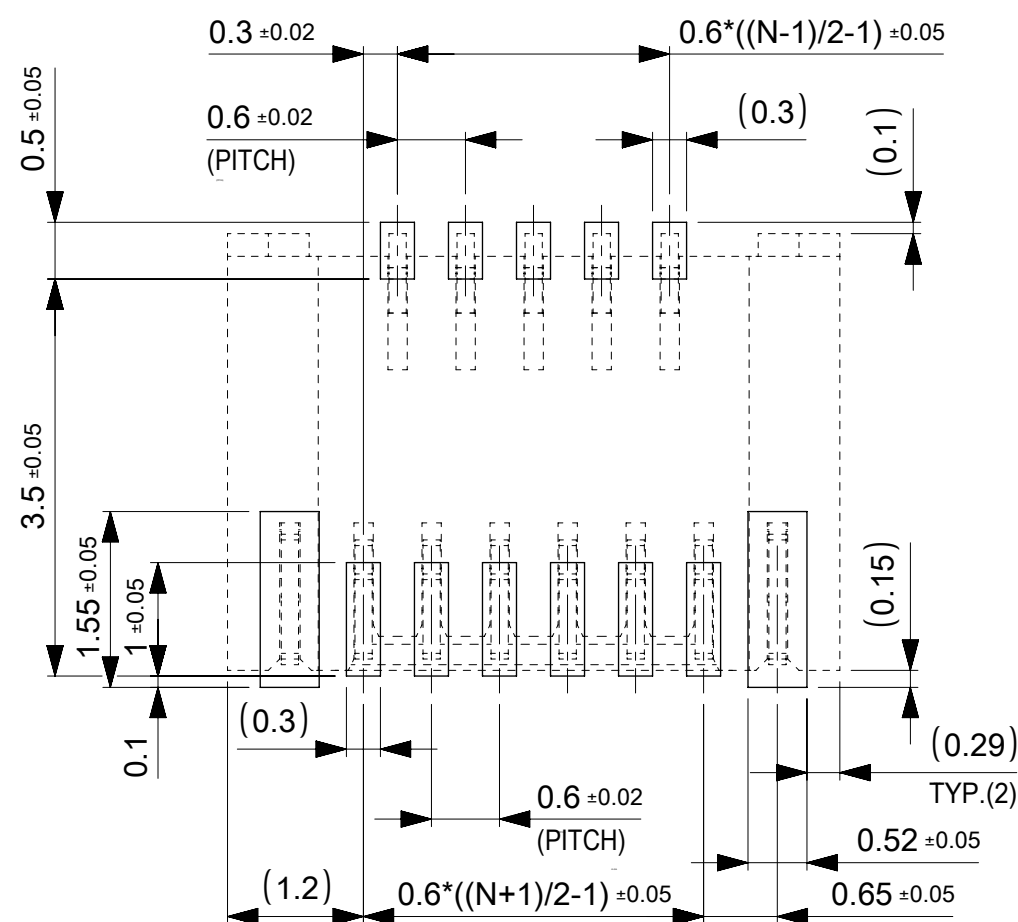
DOCUMENT NUMBER	DOC TYPE	DOC PART	REVISION
5019120000	PSD	000	B1

DOCUMENT STATUS	P1	RELEASE DATE	2024/05/13	16:22:02
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15.6	14.4	15.0	17.4	5019125190	5019125110	51
13.8	12.6	13.2	15.6	5019124590	5019124510	45
12.6	11.4	12.0	14.4	5019124190	5019124110	41
12.0	10.8	11.4	13.8	-----	5019123910	39
11.4	10.2	10.8	13.2	5019123790	5019123710	37
10.8	9.6	10.2	12.6	-----	5019123510	35
10.2	9.0	9.6	12.0	-----	5019123310	33
8.4	7.2	7.8	10.2	5019122790	5019122710	27
7.8	6.6	7.2	9.6	5019122590	5019122510	25
7.2	6.0	6.6	9.0	5019122390	5019122310	23
6.6	5.4	6.0	8.4	5019122190	5019122110	21
4.8	3.6	4.2	6.6	5019121590	5019121510	15
D	C	B	A	EMBOSSED TAPE PKG	MATERIAL No.	CIRCUIT
				ORDER No.		
MODEL No. 501912**10						

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						
DIMENSION UNITS	SCALE	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#513405.				
mm	15:1					
GENERAL TOLERANCES (UNLESS SPECIFIED)						
ANGULAR TOL	± 3.0 °					
4 PLACES	± 0.2					
3 PLACES	± 0.2					
2 PLACES	± 0.2					
1 PLACE	± 0.2					
0 PLACES	± 0.2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER
			A3-SIZE	501912	SEE TABLE	
				2015/11/24	5019121000	PSD 000 B1
				2016/01/05		
				1 OF 2		

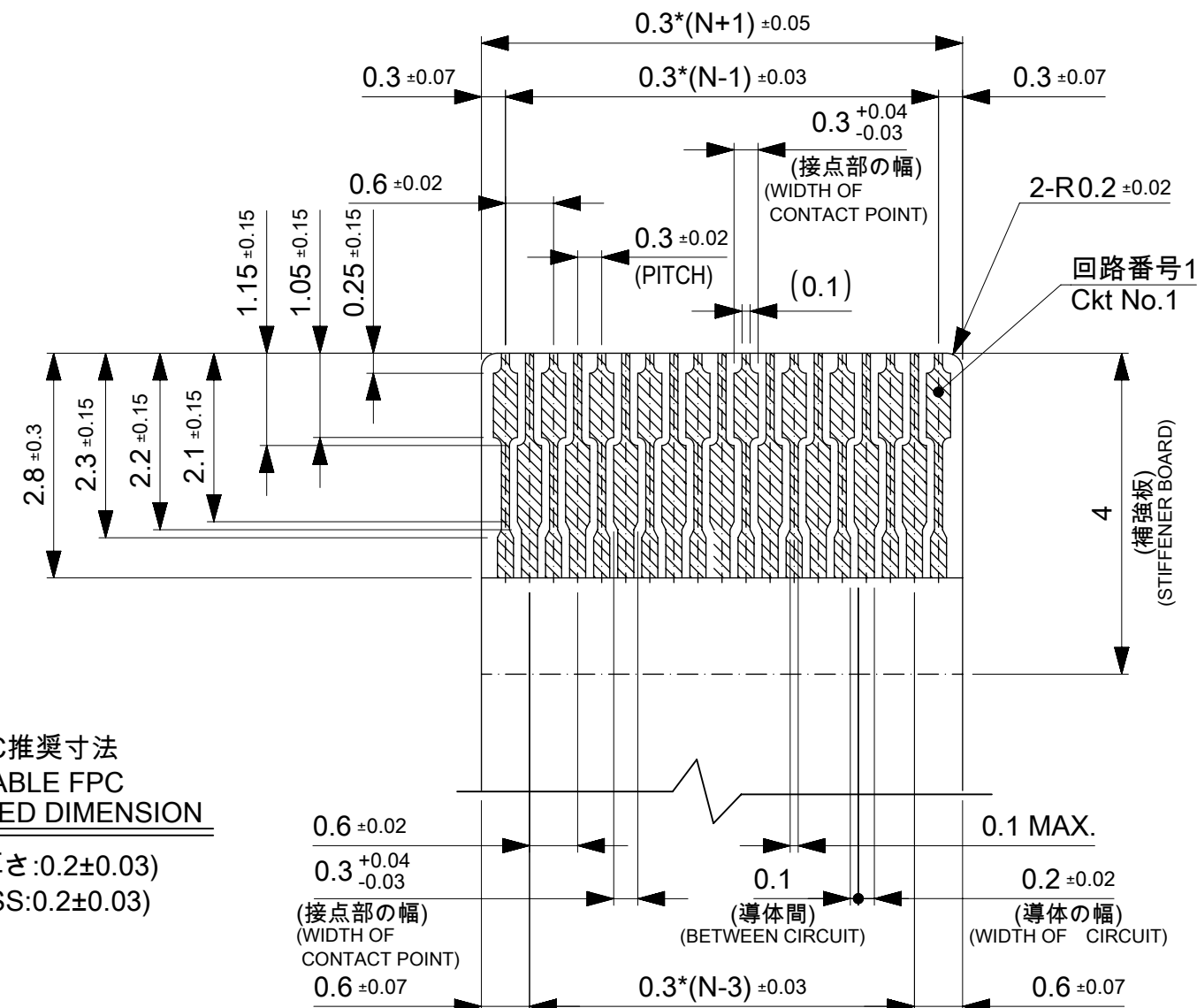


参考基板レイアウト図
(マウント面)
(MOUNTING SIDE)

注記 NOTES

1. 使用材料 MATERIAL

- ハウジング :耐熱性樹脂 ガラス充填 UL94V-0
 HOUSING :HEAT RESISTANCE POLYMER(GLASS FILLED) UL94V-0
 アクチュエータ :耐熱性樹脂 ガラス充填 UL94V-0
 ACTUATOR :HEAT RESISTANCE POLYMER(GLASS FILLED) UL94V-0
 ターミナル :銅合金(t=0.15)、ニッケル下地金メッキ
 TERMINAL :COPPER ALLOY(t=0.15),GOLD OVER NICKEL PLATING.
 金具 :銅合金(t=0.15)、ニッケル下地スズメッキ
 FITTING NAIL :COPPER ALLOY(t=0.15),TIN OVER NICKEL PLATING.
 ハウジングに黒点がある場合がありますが、問題はありません。
2. ソルダータール半田付け面、及び金具半田付け面の平坦度 : 0.1mm MAXIMUM.
 COPLANARITY OF SOLDER TAILS AND FITTING NAILS TO BE 0.1mm MAXIMUM.
3. ELV AND RoHS COMPLIANT.



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION

(仕上がり厚さ:0.2±0.03)
(THICKNESS:0.2±0.03)

FPCについて:

打抜き方向は導体側から補強板側を推奨致します。

導体部については軟銅箔35マイクロメートルまたは50マイクロメートルを推奨致します。

補強フィルム材質はポリイミドを推奨します。

接着剤は熱硬化接着剤を推奨します。

ABOUT FPC

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.

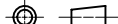
RECOMMENDED CONDUCTOR SPEC :

THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.

RECOMMENDED MATERIAL :

STIFFENER FILM : POLYIMIDE

BONDING AGENT : THERMOSETTING BONDING AGENT.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									
DIMENSION UNITS mm		SCALE 15:1		CURRENT REV DESC: REMOVED OBSOLETED PART NUMBERS AS PER PCN#513405. EC NO: 784316 DRWN: RAVINR12024/04/19 CHK'D: GGA2024/05/13 APPR: GGA2024/05/13 INITIAL REVISION: DRWN: SHIRATA2015/11/24 APPR: YNOGAWA2016/01/05			molex		
GENERAL TOLERANCES (UNLESS SPECIFIED)		0.3 FPC CONN E/O HSG ASSY (HGT=1.8MM) GOLD PLATING							
ANGULAR TOL ± 3.0°									
4 PLACES ± 0.2		PRODUCT CUSTOMER DRAWING							
3 PLACES ± 0.2									
2 PLACES ± 0.2									
1 PLACE ± 0.2									
0 PLACES ± 0.2		DOCUMENT NUMBER 5019121000			DOC TYPE PSD	DOC PART 000	REVISION B1		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION 	DRAWING A3-SIZE	SERIES 501912	MATERIAL NUMBER SEE TABLE	CUSTOMER		SHEET NUMBER 2 OF 2	